

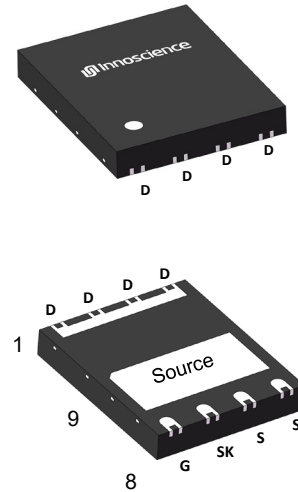
# INN700DA190B

## 1. General description

700V GaN-on-Silicon Enhancement-mode Power Transistor in Dual Flat No-lead package (DFN) with 5 mm × 6 mm size

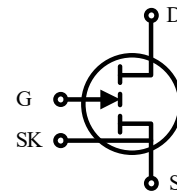
## 2. Features

- Enhancement mode transistor-Normally off power switch
- Ultra high switching frequency
- No reverse-recovery charge
- Low gate charge, low output charge
- Qualified for industrial applications according to JEDEC Standards
- ESD safeguard
- RoHS, Pb-free, REACH-compliant



## 3. Applications

- DCM/BCM PFC
- AHB/LLC/QR Flyback/ACF DCDC converter
- LED driver
- Fast battery charger
- Notebook/AIO adaptor
- Desktop PC/ATX/TV/power tool power supply



## 4. Key performance parameters

**Table 1** Key performance parameters at  $T_j = 25\text{ }^\circ\text{C}$

Parameter	Value	Unit
$V_{DS,max}$	700	V
$R_{DS(on),max}$ @ $V_{GS} = 6\text{ V}$	190	m $\Omega$
$Q_{G,typ}$ @ $V_{DS} = 400\text{ V}$	2.8	nC
$I_{D,pulse}$	20.5	A
$Q_{OSS}$ @ $V_{DS} = 400\text{ V}$	24.5	nC
$Q_{rr}$ @ $V_{DS} = 400\text{ V}$	0	nC

## 5. Pin information

**Table 2** Pin information

Gate	Drain	Kelvin Source	Source
8	1,2,3,4	7	5,6,9

**Table 3** Ordering information

Type/Ordering Code	Package	Product Code
INN700DA190B	DFN 5X6	70DA190B

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## 6. Maximum ratings

at  $T_j = 25\text{ °C}$  unless otherwise specified

Exceeding the maximum ratings may destroy the device. For further information, contact Innoscence sales office

**Table 4** Maximum ratings

Parameter	Symbol	Values	Unit	Note/Test Condition
Drain source voltage	$V_{DS,max}$	700	V	$V_{GS} = 0\text{ V}$ , $T_j = -55\text{ °C}$ to $150\text{ °C}$
Drain source voltage transient <sup>1</sup>	$V_{DS,transient}$	800	V	$V_{GS} = 0\text{ V}$
Drain source voltage, pulsed <sup>2</sup>	$V_{DS,pulse}$	750	V	$T_j = 25\text{ °C}$ ; total time < 10 h
				$T_j = 125\text{ °C}$ ; total time < 1 h
Continuous current, drain source	$I_D$	11.5	A	$T_c = 25\text{ °C}$
Pulsed current, drain source <sup>3</sup>	$I_{D,pulse}$	20.5	A	$T_c = 25\text{ °C}$ ; $V_{GS} = 6\text{ V}$ ; $t_{PULSE} = 10\text{ }\mu\text{s}$
Pulsed current, drain source <sup>3</sup>	$I_{D,pulse}$	11.5	A	$T_c = 125\text{ °C}$ ; $V_{GS} = 6\text{ V}$ ; $t_{PULSE} = 10\text{ }\mu\text{s}$
Gate source voltage, continuous <sup>4</sup>	$V_{GS}$	-1.4 to +7	V	$T_j = -55\text{ °C}$ to $150\text{ °C}$
Gate source voltage, pulsed	$V_{GS,pulse}$	-20 to +10	V	$T_j = -55\text{ °C}$ to $150\text{ °C}$ ; $t_{PULSE} = 50\text{ ns}$ , $f = 100\text{ kHz}$ ; open drain
Power dissipation	$P_{tot}$	82	W	$T_c = 25\text{ °C}$
Operating temperature	$T_j$	-55 to +150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	

1  $V_{DS,transient}$  is intended for non-repetitive events,  $t_{PULSE} < 200\text{ }\mu\text{s}$

2  $V_{DS,pulse}$  is intended for repetitive pulse,  $t_{PULSE} < 100\text{ ns}$

3 Limit was extracted from characterization test, not measured during production

4 The minimum  $V_{GS}$  is clamped by ESD protection circuit, as shown in Figure 10

## 7. Thermal characteristics

**Table 5 Thermal characteristics**

Parameter	Symbol	Values	Unit	Note/Test Condition
Thermal resistance, junction-ambient	$R_{thJA}^1$	70	°C/W	
Thermal resistance, junction-case	$R_{thJC}$	1.52	°C/W	
Maximum reflow soldering temperature	$T_{sold}$	260	°C	MSL3

1. $R_{thJA}$  is determined with the device mounted on one square inch of copper pad, single layer 2oz copper on FR4 board.

## 8. Electric characteristics

at  $T_j = 25\text{ °C}$ , unless specified otherwise

**Table 6** Static characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Gate threshold voltage	$V_{GS(th)}$	1.2	1.7	2.5	V	$I_D = 12.2\text{ mA}; V_{DS} = V_{GS}; T_j = 25\text{ °C}$
		-	1.7	-		$I_D = 12.2\text{ mA}; V_{DS} = V_{GS}; T_j = 150\text{ °C}$
Drain-source leakage current	$I_{DSS}$	-	0.45	20	$\mu\text{A}$	$V_{DS} = 700\text{ V}; V_{GS} = 0\text{ V}; T_j = 25\text{ °C}$
		-	6	-		$V_{DS} = 700\text{ V}; V_{GS} = 0\text{ V}; T_j = 150\text{ °C}$
Gate-source leakage current	$I_{GSS}$	-	60	-	$\mu\text{A}$	$V_{GS} = 6\text{ V}; V_{DS} = 0\text{ V}$
Drain-source on-state resistance	$R_{DS(on)}$	-	138	190	m $\Omega$	$V_{GS} = 6\text{ V}; I_D = 3.9\text{ A}; T_j = 25\text{ °C}$
		-	300	-		$V_{GS} = 6\text{ V}; I_D = 3.9\text{ A}; T_j = 150\text{ °C}$
Gate resistance	$R_G$	-	5.8	-	$\Omega$	$f = 5\text{ MHz}; \text{open drain}$

**Table 7** Dynamic characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{iss}$	-	96	-	pF	$V_{GS} = 0\text{ V}; V_{DS} = 400\text{ V}; f = 100\text{ kHz}$
Output capacitance	$C_{oss}$	-	30	-	pF	$V_{GS} = 0\text{ V}; V_{DS} = 400\text{ V}; f = 100\text{ kHz}$
Reverse transfer Capacitance	$C_{rss}$	-	0.5	-	pF	$V_{GS} = 0\text{ V}; V_{DS} = 400\text{ V}; f = 100\text{ kHz}$
Effective output capacitance, energy related <sup>1</sup>	$C_{o(er)}$	-	43	-	pF	$V_{GS} = 0\text{ V}; V_{DS} = 0\text{ to }400\text{ V}$
Effective output capacitance, time related <sup>2</sup>	$C_{o(tr)}$	-	60	-	pF	$V_{GS} = 0\text{ V}; V_{DS} = 0\text{ to }400\text{ V}$
Output charge	$Q_{OSS}$	-	24.5	-	nC	$V_{GS} = 0\text{ V}; V_{DS} = 0\text{ to }400\text{ V}$
Turn-on delay time	$t_{d(on)}$	-	1.4	-	ns	$V_{DS} = 400\text{ V}; I_D = 8\text{ A}; L = 318\text{ }\mu\text{H};$ $V_{GS} = 6\text{ V}; R_{on} = 10\text{ }\Omega; R_{off} = 2\text{ }\Omega;$ See Figure 22
Turn-off delay time	$t_{d(off)}$	-	1.7	-	ns	
Rise time	$t_r$	-	4.0	-	ns	
Fall time	$t_f$	-	4.0	-	ns	

- $C_{o(er)}$  is the fixed capacitance that gives the same stored energy as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 400 V
- $C_{o(tr)}$  is the fixed capacitance that gives the same charging time as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 400 V

**Table 8 Gate charge characteristics**

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Gate charge	$Q_G$	-	2.8	-	nC	$V_{GS} = 0$ to 6 V; $V_{DS} = 400$ V; $I_D = 3.9$ A
Gate-source charge	$Q_{GS}$	-	0.25	-	nC	
Gate-drain charge	$Q_{GD}$	-	1.1	-	nC	
Gate Plateau Voltage	$V_{Plat}$	-	2.2	-	V	$V_{DS} = 400$ V; $I_D = 3.9$ A

**Table 9 Reverse conduction characteristics**

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Source-Drain reverse voltage	$V_{SD}$	-	2.6	-	V	$V_{GS} = 0$ V; $I_S = 3.9$ A
Pulsed current, reverse	$I_{S,pulse}$	-	-	20.5	A	$V_{GS} = 6$ V; $t_{PULSE} = 10$ $\mu$ s
Reverse recovery charge	$Q_{rr}$	-	0	-	nC	$I_S = 3.9$ A; $V_{DS} = 400$ V
Reverse recovery time	$t_{rr}$	-	0	-	ns	
Peak reverse recovery current	$I_{rrm}$	-	0	-	A	

## 9. Electric characteristics diagrams

at  $T_j = 25\text{ }^\circ\text{C}$ , unless specified otherwise

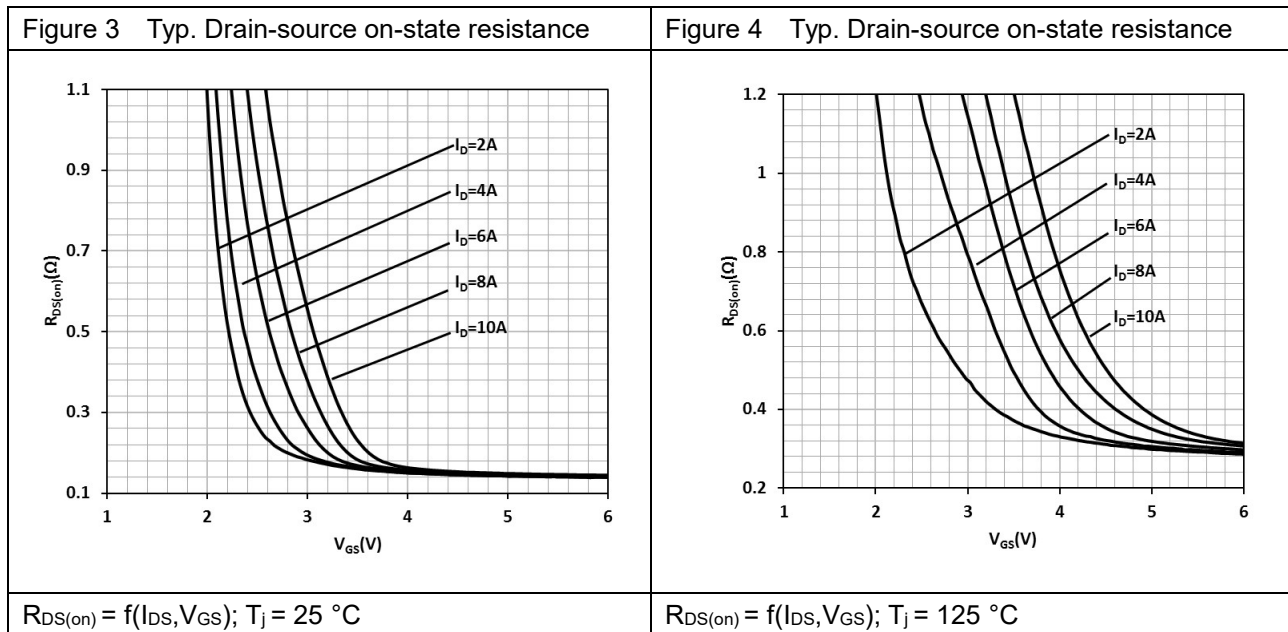
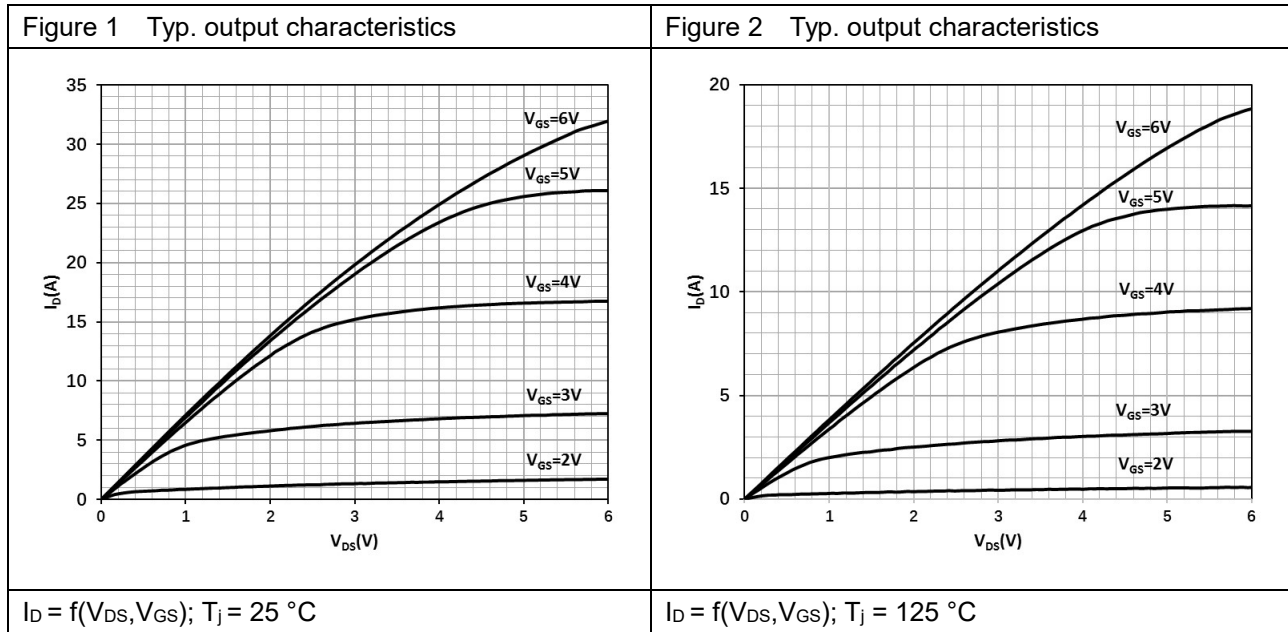
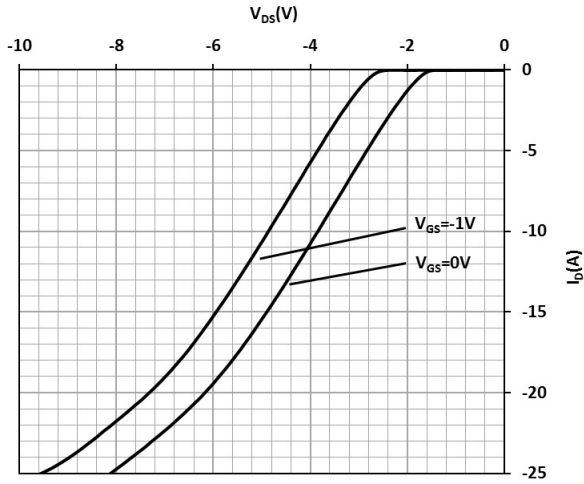
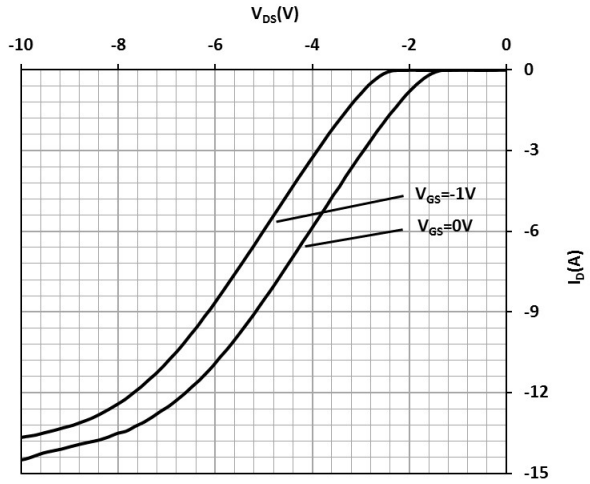


Figure 5 Typ. channel reverse characteristics



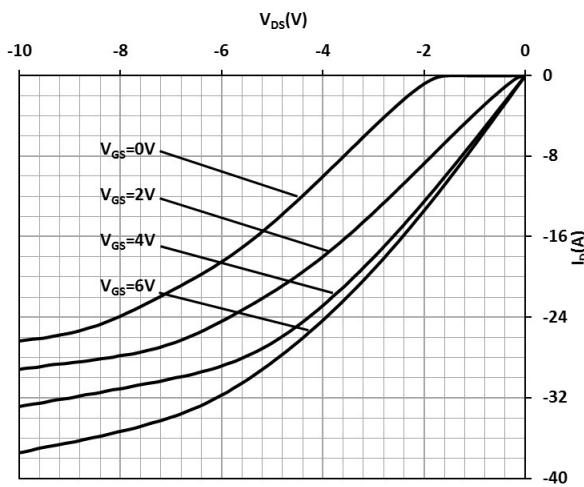
$I_D = f(V_{DS}, V_{GS}); T_j = 25\text{ }^\circ\text{C}$

Figure 6 Typ. channel reverse characteristics



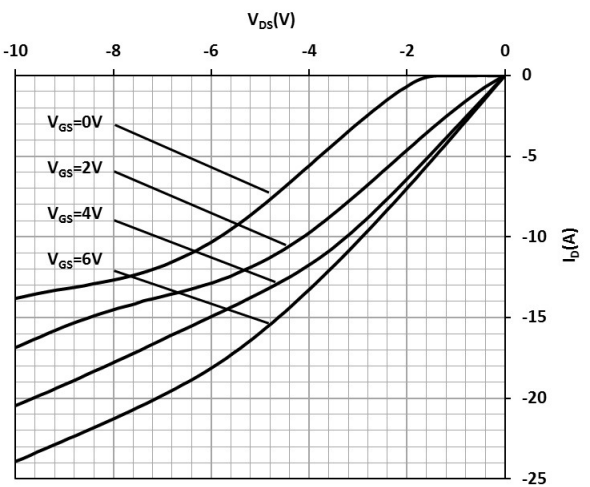
$I_D = f(V_{DS}, V_{GS}); T_j = 125\text{ }^\circ\text{C}$

Figure 7 Typ. channel reverse characteristics



$I_D = f(V_{DS}, V_{GS}); T_j = 25\text{ }^\circ\text{C}$

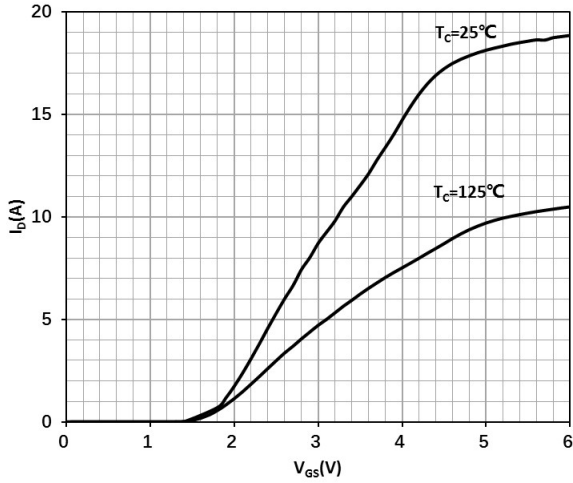
Figure 8 Typ. channel reverse characteristics



$I_D = f(V_{DS}, V_{GS}); T_j = 125\text{ }^\circ\text{C}$

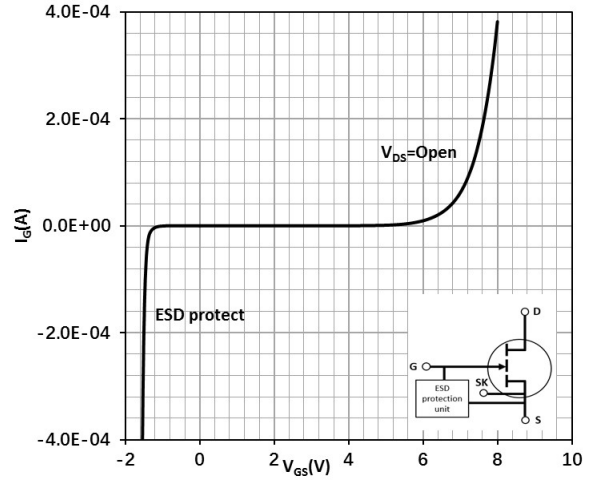


Figure 9 Typ. transfer characteristics



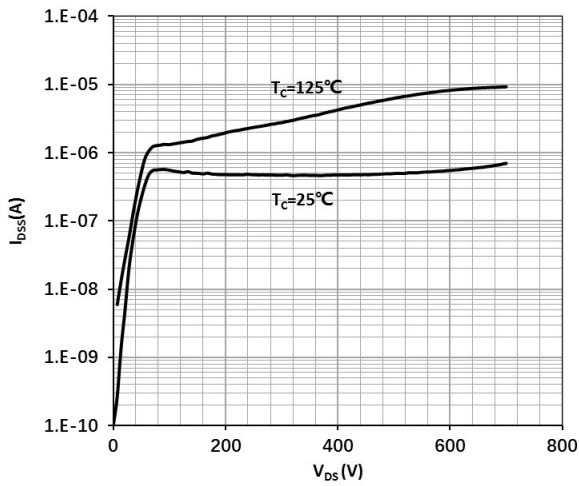
$I_D = f(V_{GS}); V_{DS} = 3\text{ V}$

Figure 10 Typ. Gate-to-Source leakage



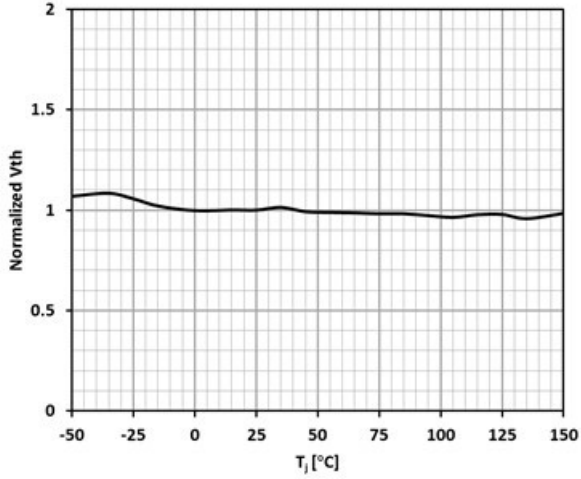
$I_G = f(V_{GS}); I_G$  reverse turn on by ESD unit

Figure 11 Drain-source leakage characteristics



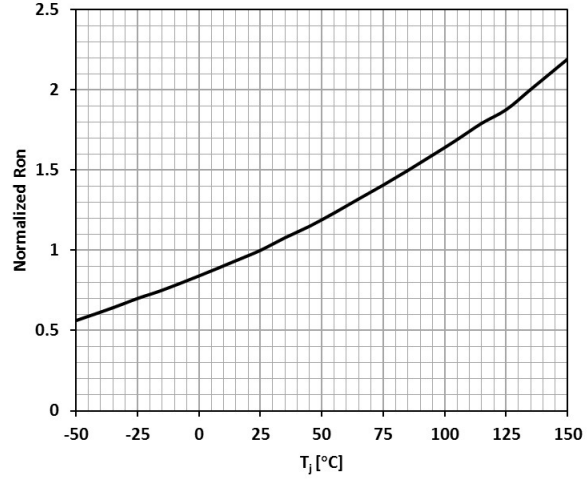
$I_{DSS} = f(V_{DS}); V_{GS} = 0\text{ V}$

Figure 12 Gate threshold voltage



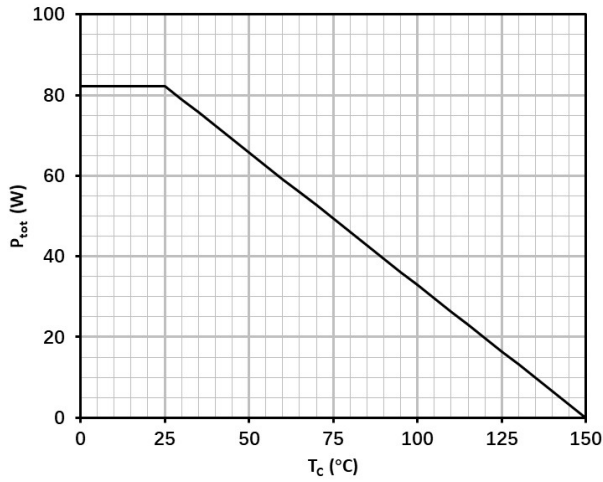
$V_{TH} = f(T_j); V_{GS} = V_{DS}; I_D = 12.2 \text{ mA}$

Figure 13 Drain-source on-state resistance



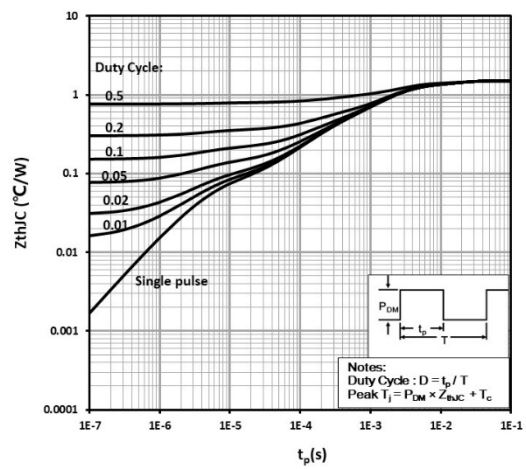
$R_{DS(on)} = f(T_j); I_D = 3.9 \text{ A}; V_{GS}=6\text{V}$

Figure 14 Power dissipation



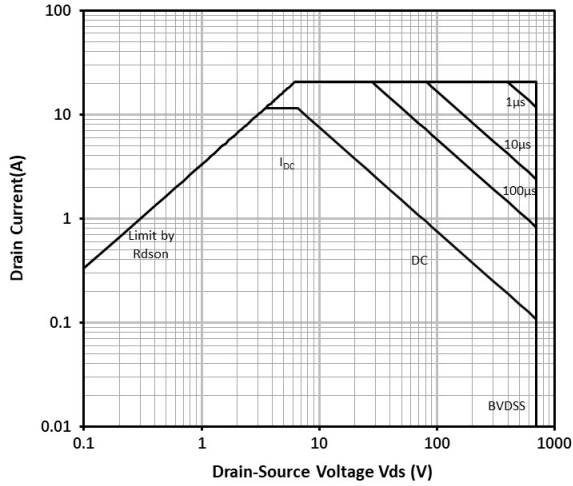
$P_{tot} = f(T_c)$

Figure 15 Max.transient thermal impedance



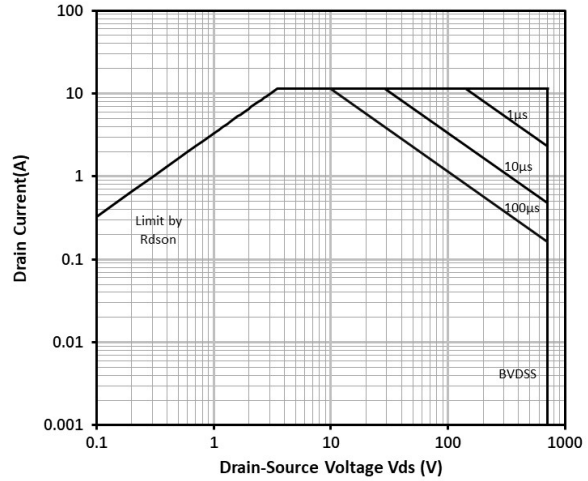
$Z_{thJC} = f(t_p, D)$

Figure 16 Safe operating area



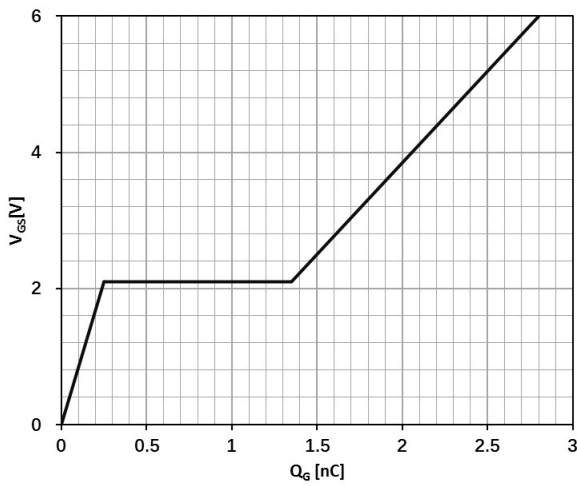
$I_D = f(V_{DS}); T_C = 25\text{ °C}$

Figure 17 Safe operating area



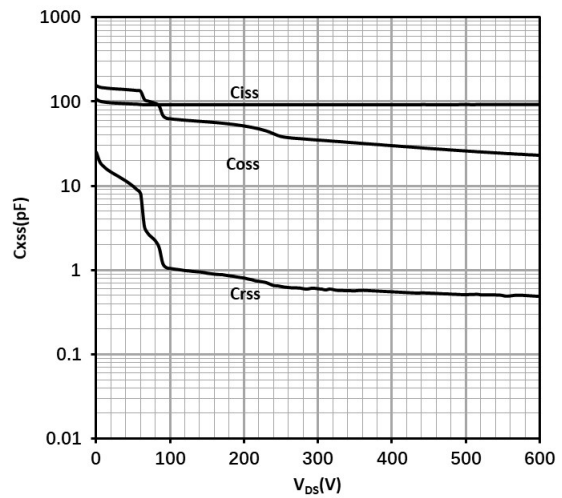
$I_D = f(V_{DS}); T_C = 125\text{ °C}$

Figure 18 Typ. gate charge



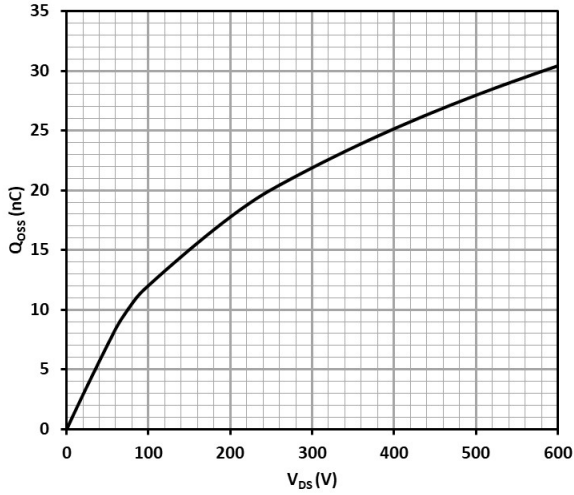
$V_{GS} = f(Q_G); V_{DCLINK} = 400\text{ V}; I_D = 5\text{ A}$

Figure 19 Typ. capacitances



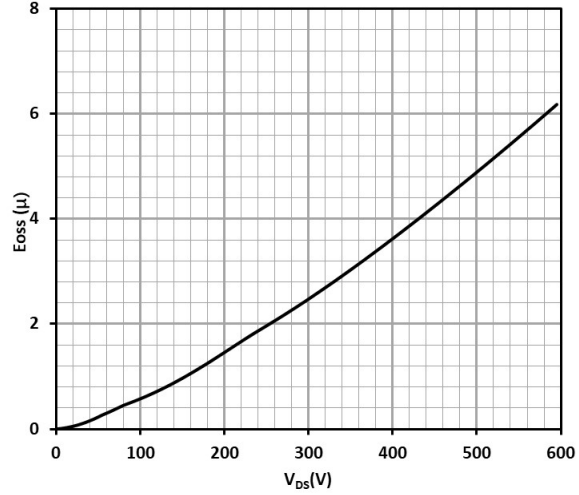
$C_{XSS} = f(V_{DS}); \text{Freq.} = 100\text{ kHz}$

Figure 20 Typ. output charge



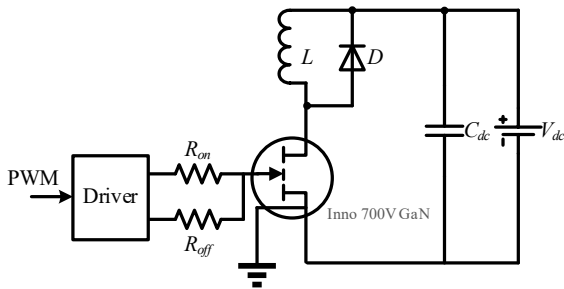
$Q_{oss} = f(V_{DS}); \text{Freq.} = 100 \text{ kHz}$

Figure 21 Typ. Coss stored Energy



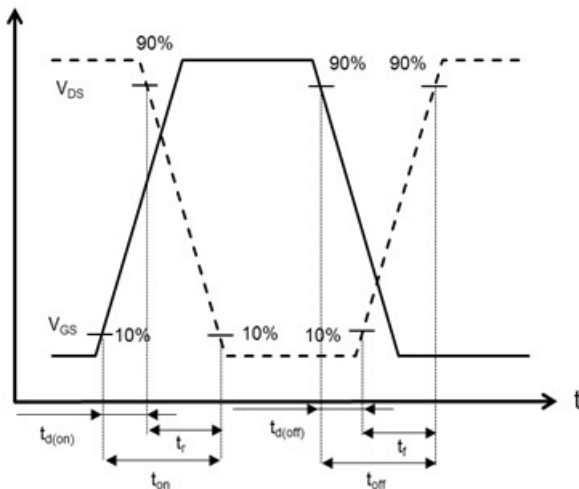
$E_{oss} = f(V_{DS}); \text{Freq.} = 100 \text{ kHz}$

Figure 22 Typ. Switching times with inductive load

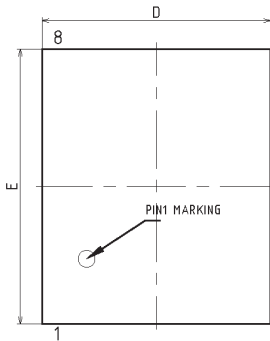


$V_{DS} = 400 \text{ V}, I_D = 8 \text{ A}, L = 318 \mu\text{H}, V_{GS} = 6 \text{ V},$   
 $R_{on} = 10 \Omega, R_{off} = 2 \Omega$

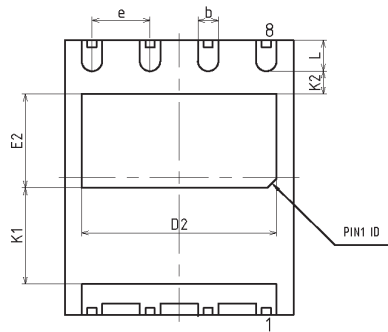
Figure 23 Typ. Switching times waveform



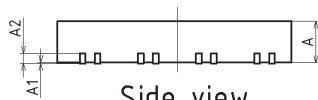
## 10. Package outlines



Top view

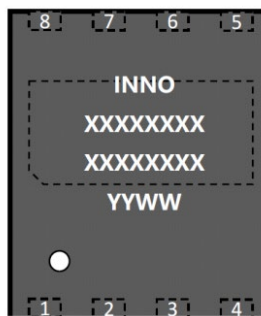


Bottom view



Side view

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A2	0.203REF		
b	0.40	0.45	0.50
D	4.90	5.00	5.10
D2	4.16	4.26	4.36
e	1.27		
E	5.90	6.00	6.10
E2	1.95	2.05	2.15
L	0.575	0.675	0.775
K1	2.10REF		
K2	0.50REF		

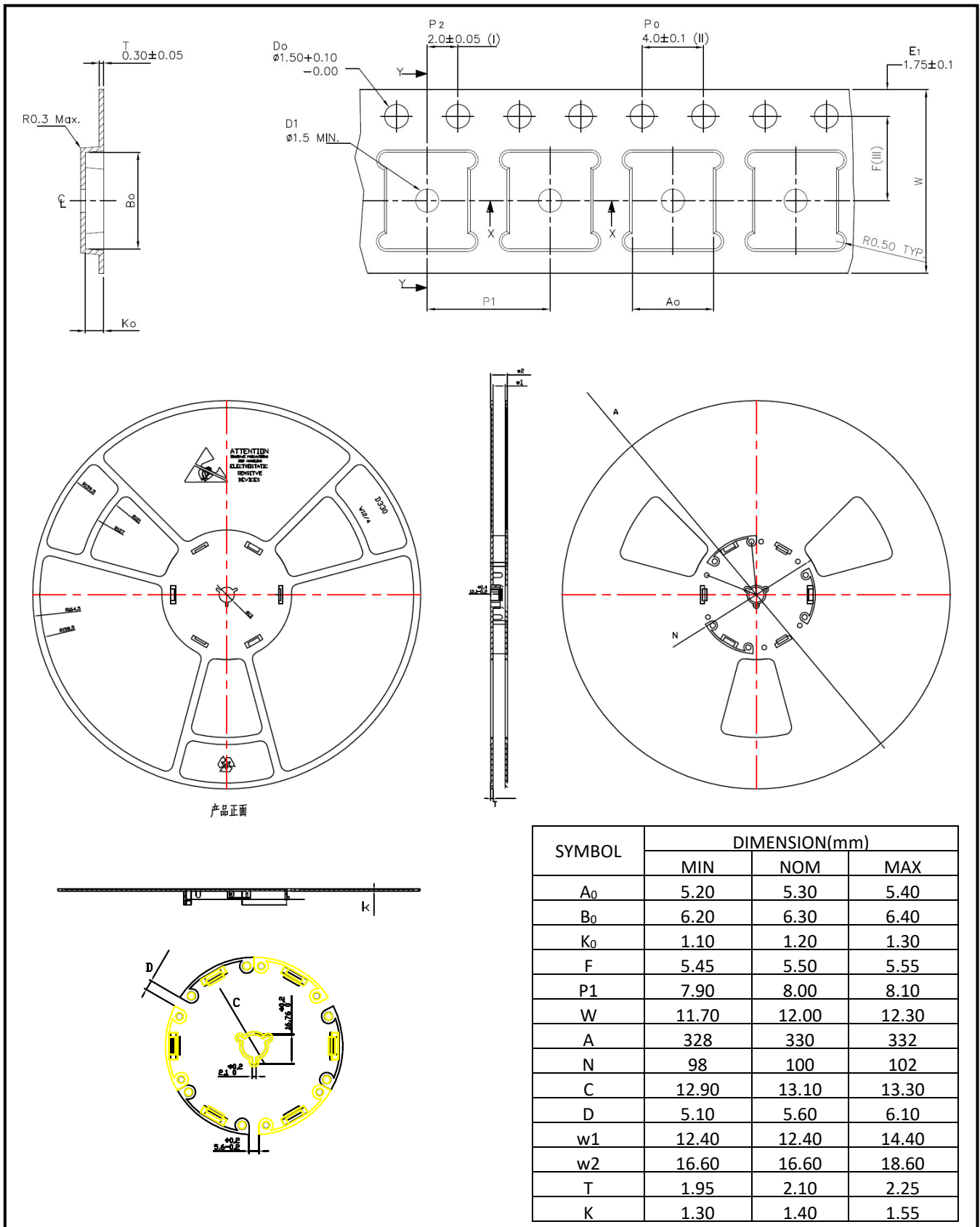


Row	Description	Example
Row1	Company name	INNO
Row2	Product code (In short)	XXXXXXXX
Row3	ASSY lot No.	XXXXXXXX
Row4	Date code	YYWW

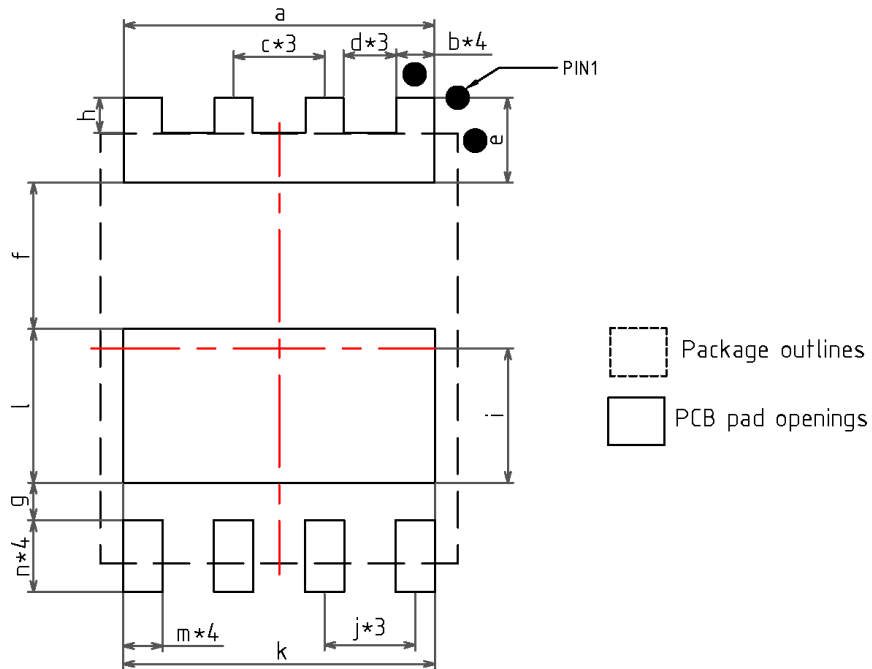
**Notes:**

- (1) Dimension and tolerance conform to ASME Y14.5-2009.
- (2) All dimension are in millimeters.
- (3) Lead coplanarity shall be 0.1 millimeters max.
- (4) Complies with JEDEC MO-229.
- (5) Drawing is not to scale.
- (6) Dimensions do not include mold protrusion.
- (7) Package outline exclusive of metal burr dimensions.

## 11. Reel information



## 12. Recommended PCB footprint



SYMBOL	DIMENSION	SYMBOL	DIMENSION
a	4.340	h	0.490
b	0.530	i	1.875
c	1.270	j	1.270
d	0.740	k	4.360
e	1.190	l	2.150
f	2.040	m	0.550
g	0.525	n	1.000

Notes:  
(1) All dimensions are in millimeters.  
(2) Drawing is not to scale.

### 13. Revision history

**Major changes since the last revision**

Revision	Date	Description of changes
1.0	2023-04-21	1.0 version release



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## Important Notice

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